ies
ower Inductors
Size 080506



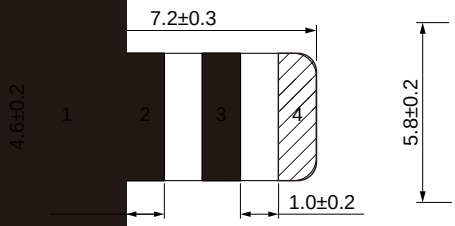
FEATURES

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- Higher current carrying Capacity, lower DCR, and more e ciency.
- Opera ng temperature: -55 to +125 °C(Including self - temperature rise).
- Quan ty: 600PCS

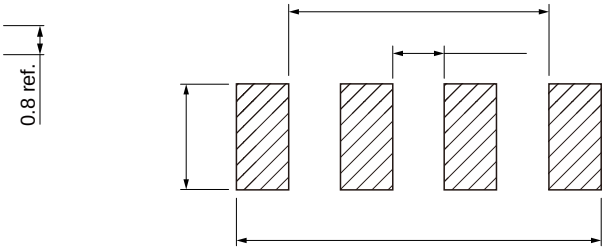
APPLICATION

- AI Servers, Data Centers, GPU/AI Accelerators.
- Desktop Motherboards, CPU/GPU Power Delivery.
- Mul -phase VRM, High-current DC-DC Converters.
- Networking Equipment, Communica on Infrastructure.

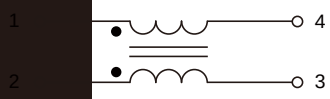
ns: [mm]



Land Pattern: [mm]



Schematic:



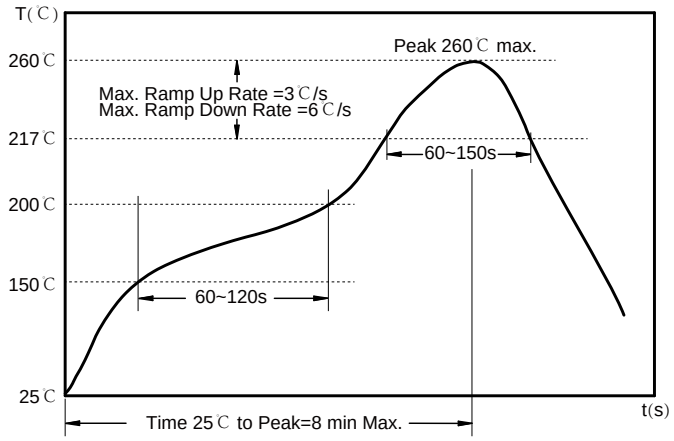
Properties:

	Inductance @ 100KHz/1V (nH)	FLL 1-4 Min. (nH)	DC Resistance 1-4 (mΩ)	DC Resistance 2-3 (mΩ)	Temperature Rise Current 1-4 Max. (A)	Satura on Current 1-4 Typ. (A)	Hi-Pot Min. (V)	Kps Typ.

referenced to 25 °C ambient.
rent will cause L0 to drop approximately 30%.
ise Current: The actual value of DC current when the temperature rise is △T=40 °C.
100 kHz, 1.0 Vrms, Isat, applied for +25 °C.
s / fail judgement, tested @ 2s,2mA, between 2 windings.

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Soldering Reflow:



Preheat condition: 150 ~200 ℃/ 60~120 sec.

Allowed time above 217 ℃: 60~150 sec.

Max temperature: 260 ℃.

Time within 5 ℃ of59 0 m-0.761

Product Marking:

Marking	Printing (Inductance)

Cautions and Warnings:

Storage Conditions:

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does.As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.